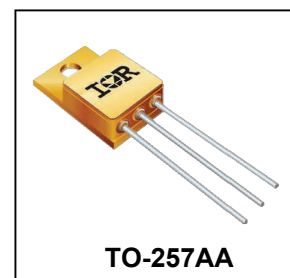


POWER MOSFET
THRU-HOLE (TO-257AA)
100V, N-CHANNEL
HEXFET® MOSFET TECHNOLOGY
Product Summary

Part Number	RDS(on)	I _D	Eyelets
IRFY140C	0.077Ω	16A*	Ceramic
IRFY140CM	0.077Ω	16A*	Ceramic


Description

HEXFET® MOSFET technology is the key to IR HiRel advanced line of power MOSFET transistors. The efficient geometry design achieves very low on-state resistance combined with high trans conductance. HEXFET® transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, high energy pulse circuits, and virtually any application where high reliability is required. The HEXFET transistor's totally isolated package eliminates the need for additional isolating material between the device and the heatsink. This improves thermal efficiency and reduces drain capacitance.

Features

- Simple Drive Requirements
- Hermetically Sealed
- Electrically Isolated
- Ceramic Eyelets
- Ideally Suited For Space Level Applications
- ESD Rating: Class 2 per MIL-STD-750, Method 1020

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I _{D1} @ V _{GS} = 10V, T _C = 25°C	Continuous Drain Current	16*	A
I _{D2} @ V _{GS} = 10V, T _C = 100°C	Continuous Drain Current	16*	
I _{DM} @ T _C = 25°C	Pulsed Drain Current ①	64	
P _D @ T _C = 25°C	Maximum Power Dissipation	100	W
	Linear Derating Factor	0.8	W/°C
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy ②	230	mJ
I _{AR}	Avalanche Current ①	16*	A
E _{AR}	Repetitive Avalanche Energy ①	10	mJ
dv/dt	Peak Diode Recovery ③	5.5	V/ns
T _J T _{STG}	Operating Junction and Storage Temperature Range	-55 to + 150	°C
	Lead Temperature	300(0.063in./1.6mm from case for 10 sec)	
	Weight	4.3 (Typical)	g

*Current is limited by package
For footnotes refer to the page 2.

Electrical Characteristics @ T_j = 25°C (Unless Otherwise Specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	100	—	—	V	V _{GS} = 0V, I _D = 1.0mA
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	—	0.1	—	V/°C	Reference to 25°C, I _D = 1.0mA
R _{DS(on)}	Static Drain-to-Source On-Resistance	—	—	0.077	Ω	V _{GS} = 10V, I _{D2} = 16A ④
V _{GS(th)}	Gate Threshold Voltage	2.0	—	4.0	V	V _{DS} = V _{GS} , I _D = 250μA
G _{fs}	Forward Transconductance	9.1	—	—	S	V _{DS} = 15V, I _{D2} = 16A ④
I _{DSS}	Zero Gate Voltage Drain Current	—	—	25	μA	V _{DS} = 80V, V _{GS} = 0V
		—	—	250		V _{DS} = 80V, V _{GS} = 0V, T _J = 125°C
I _{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	V _{GS} = 20V
	Gate-to-Source Leakage Reverse	—	—	-100		V _{GS} = -20V
Q _G	Total Gate Charge	—	—	59	nC	I _{D1} = 16A
Q _{GS}	Gate-to-Source Charge	—	—	12		V _{DS} = 50V
Q _{GD}	Gate-to-Drain ('Miller') Charge	—	—	30.7		V _{GS} = 10V
t _{d(on)}	Turn-On Delay Time	—	—	21	ns	V _{DD} = 50V
t _r	Rise Time	—	—	145		I _{D1} = 16A
t _{d(off)}	Turn-Off Delay Time	—	—	64		R _G = 9.1Ω
t _f	Fall Time	—	—	105		V _{GS} = 10V
L _S + L _D	Total Inductance	—	6.8	—	nH	Measured from drain lead (6mm/0.25in. from package) to source lead (6mm/0.25in. from package)
C _{iss}	Input Capacitance	—	1660	—	pF	V _{GS} = 0V
C _{oss}	Output Capacitance	—	550	—		V _{DS} = 25V
C _{rss}	Reverse Transfer Capacitance	—	120	—		f = 1.0MHz

Source-Drain Diode Ratings and Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	16	A	
I _{SM}	Pulsed Source Current (Body Diode) ①	—	—	100		
V _{SD}	Diode Forward Voltage	—	—	1.5	V	T _J = 25°C, I _S = 16A, V _{GS} = 0V④
t _{rr}	Reverse Recovery Time	—	—	400	ns	T _J = 25°C ,I _F = 16A,V _{DD} ≤ 50V di/dt = 100A/μs ④
Q _{rr}	Reverse Recovery Charge	—	—	2.4	μC	
Ton	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L _S +L _D)				

Thermal Resistance

Symbol	Parameter	Min.	Typ.	Max.	Units
R _{θJC}	Junction-to-Case	—	—	1.25	°C/W
R _{θCS}	Case-to-sink	—	0.21	—	
R _{θJA}	Junction-to-Ambient (Typical Socket Mount)	—	—	80	

Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② V_{DD} = 25V, starting T_J = 25°C, L = 1.8mH, Peak I_L = 16A, V_{GS} = 10V.
- ③ I_{SD} ≤ 16A, di/dt ≤ 170A/μs, V_{DD} ≤ 100V, T_J ≤ 150°C.
- ④ Pulse width ≤ 300 μs; Duty Cycle ≤ 2%

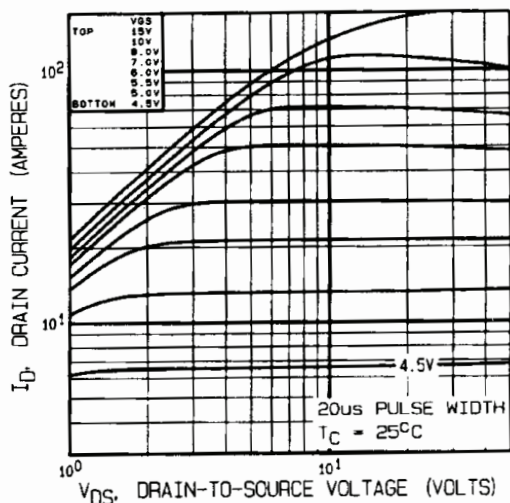


Fig 1. Typical Output Characteristics

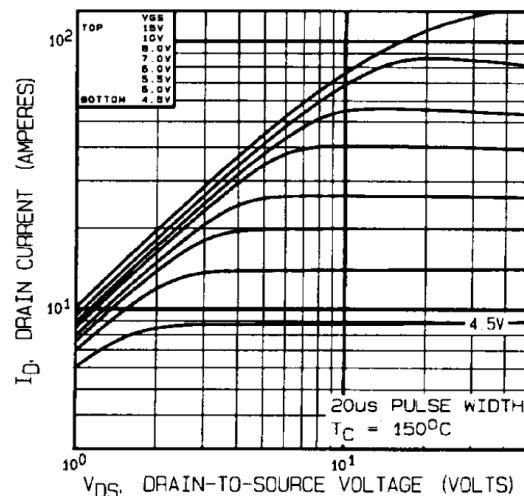


Fig 2. Typical Output Characteristics

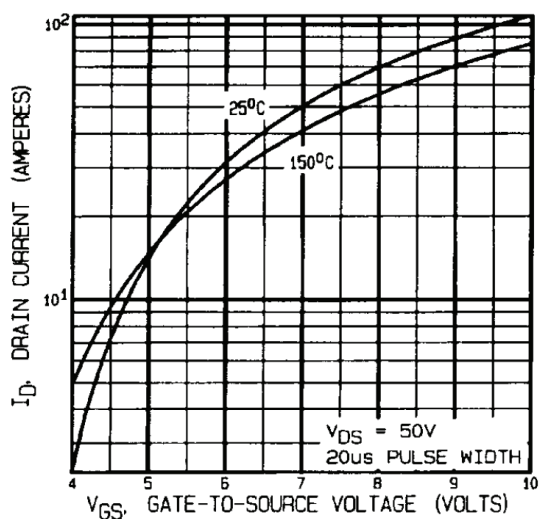


Fig 3. Typical Transfer Characteristics

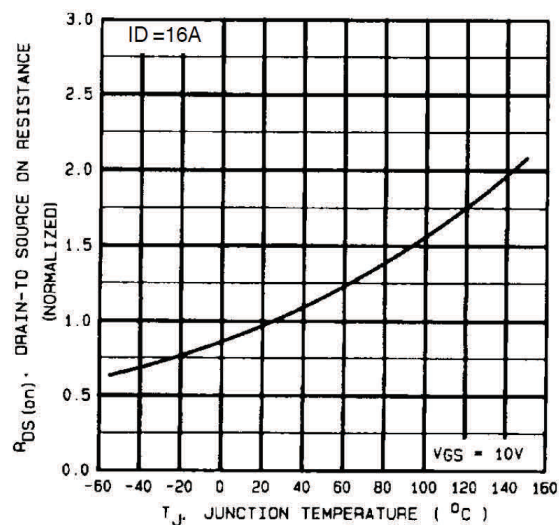


Fig 4. Normalized On-Resistance Vs. Temperature

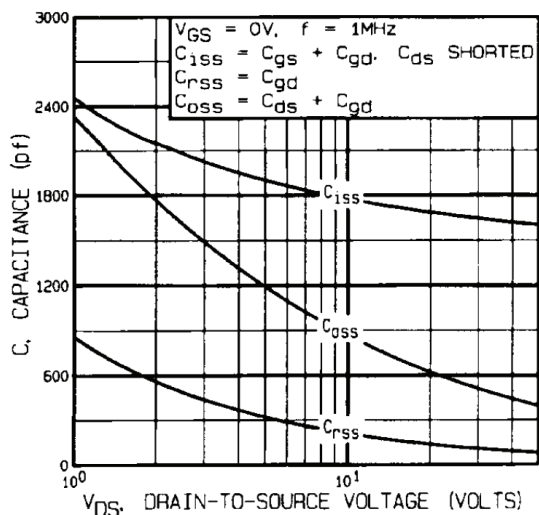


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

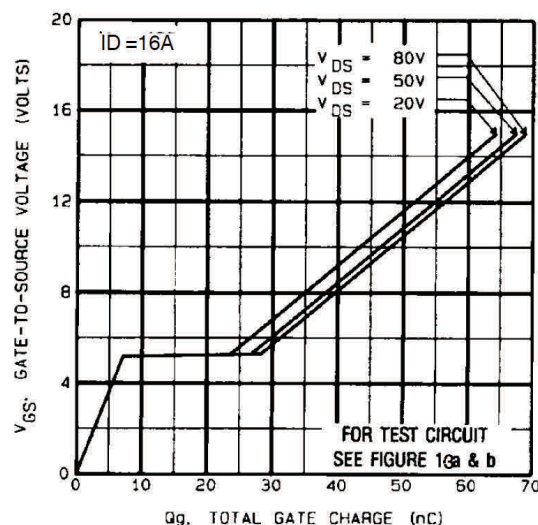


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

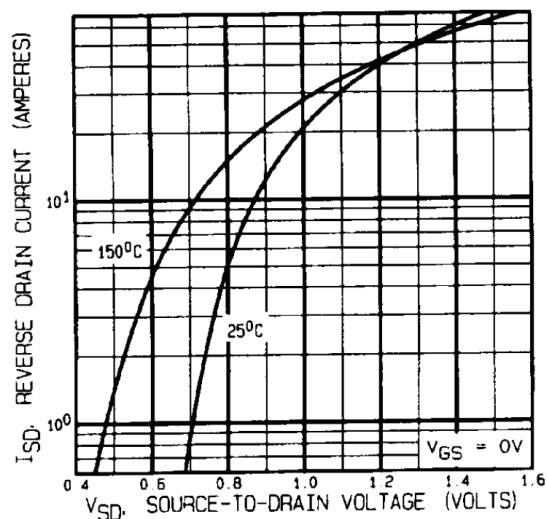


Fig 7. Typical Source-Drain Diode Forward Voltage

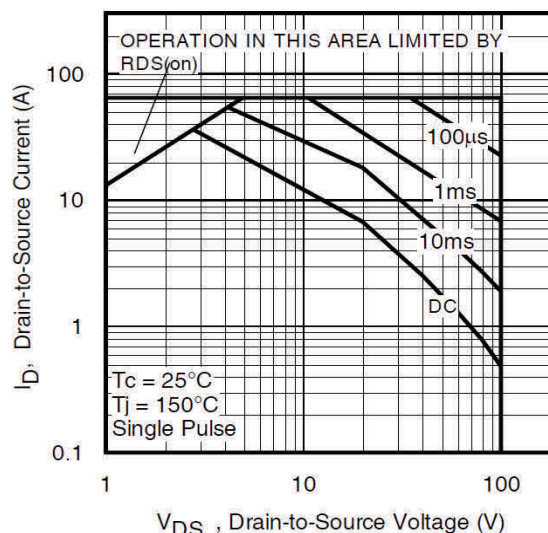


Fig 8. Maximum Safe Operating Area

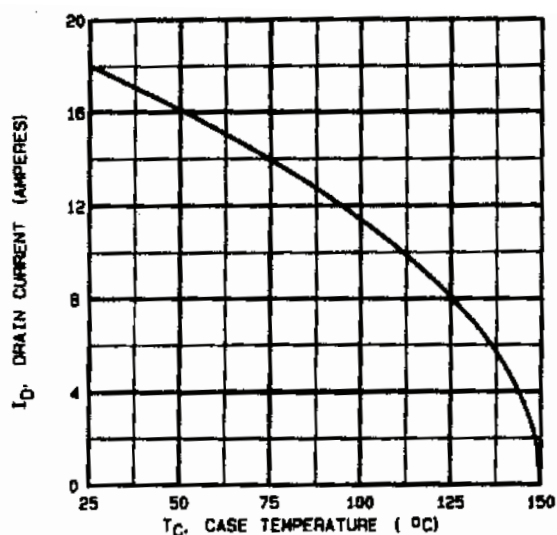


Fig 9. Maximum Drain Current Vs. Case Temperature

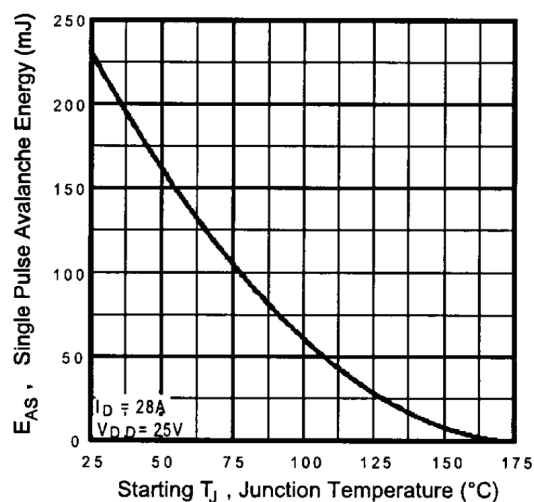


Fig 10. Maximum Avalanche Energy Vs. Drain Current

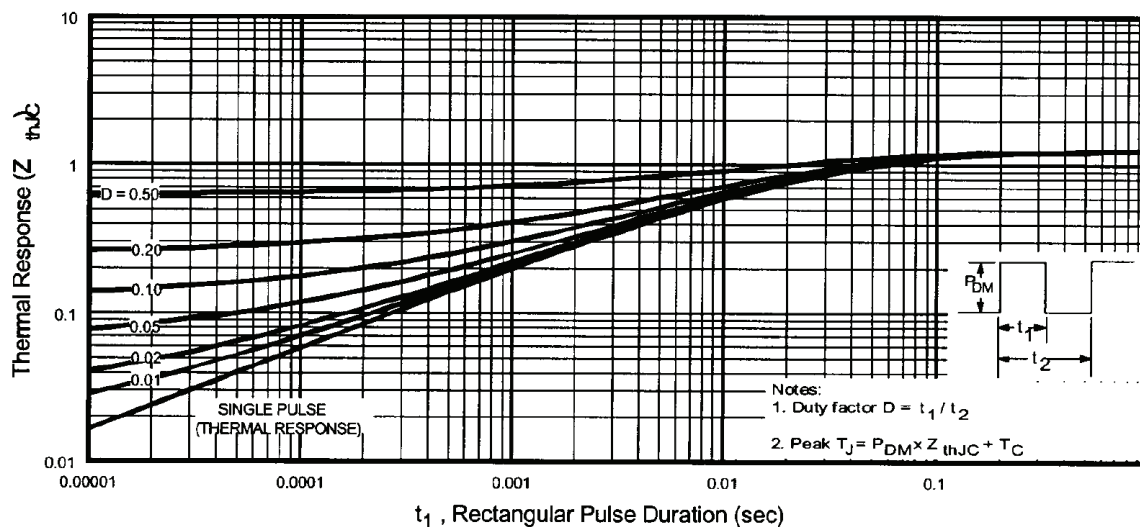


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

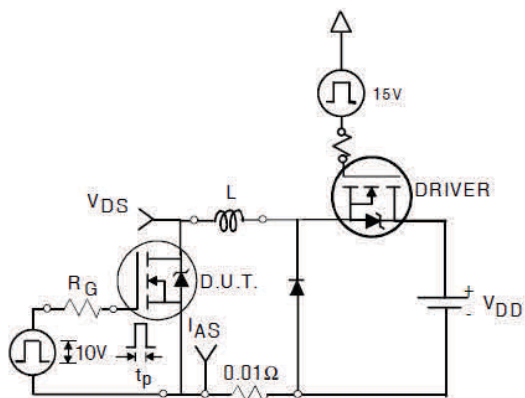


Fig 12a. Unclamped Inductive Test Circuit

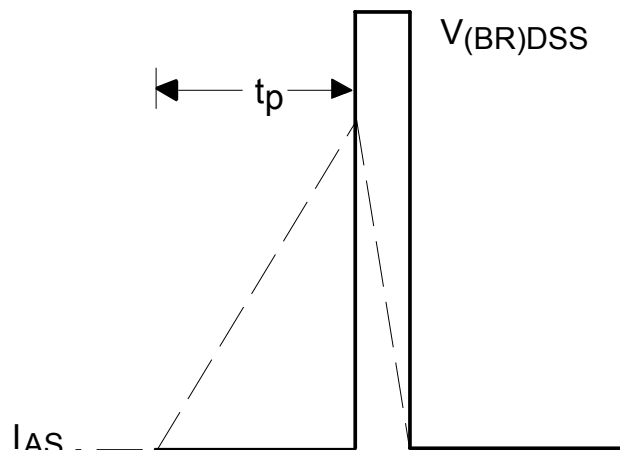


Fig 12b. Unclamped Inductive Waveforms

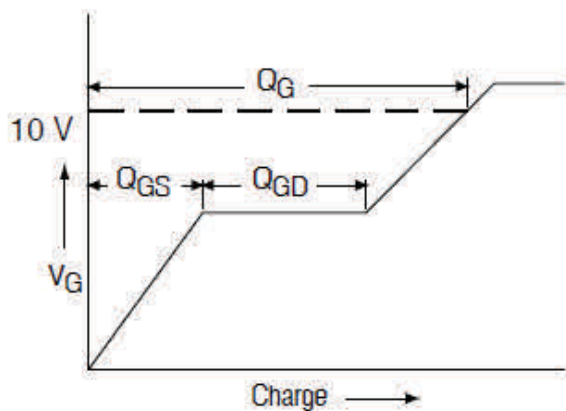


Fig 13a. Gate Charge Waveform

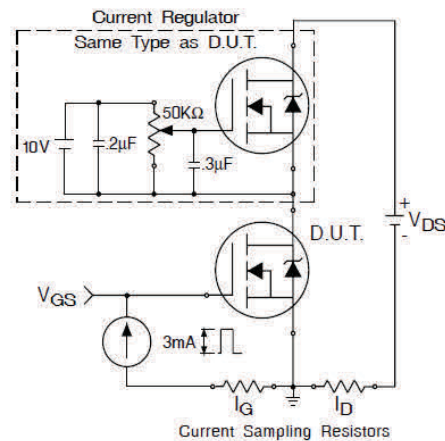


Fig 13b. Gate Charge Test Circuit

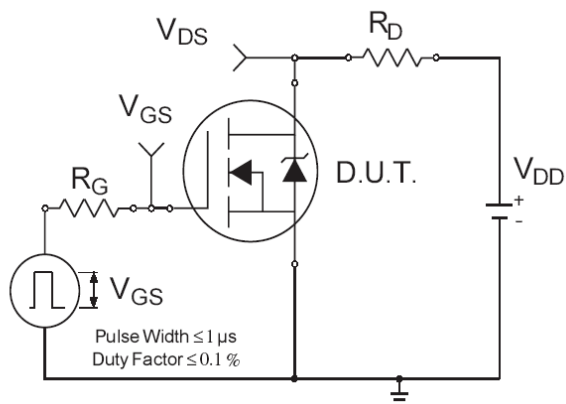


Fig 14a. Switching Time Test Circuit

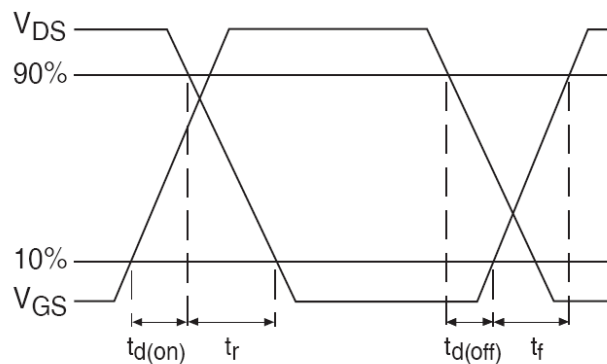
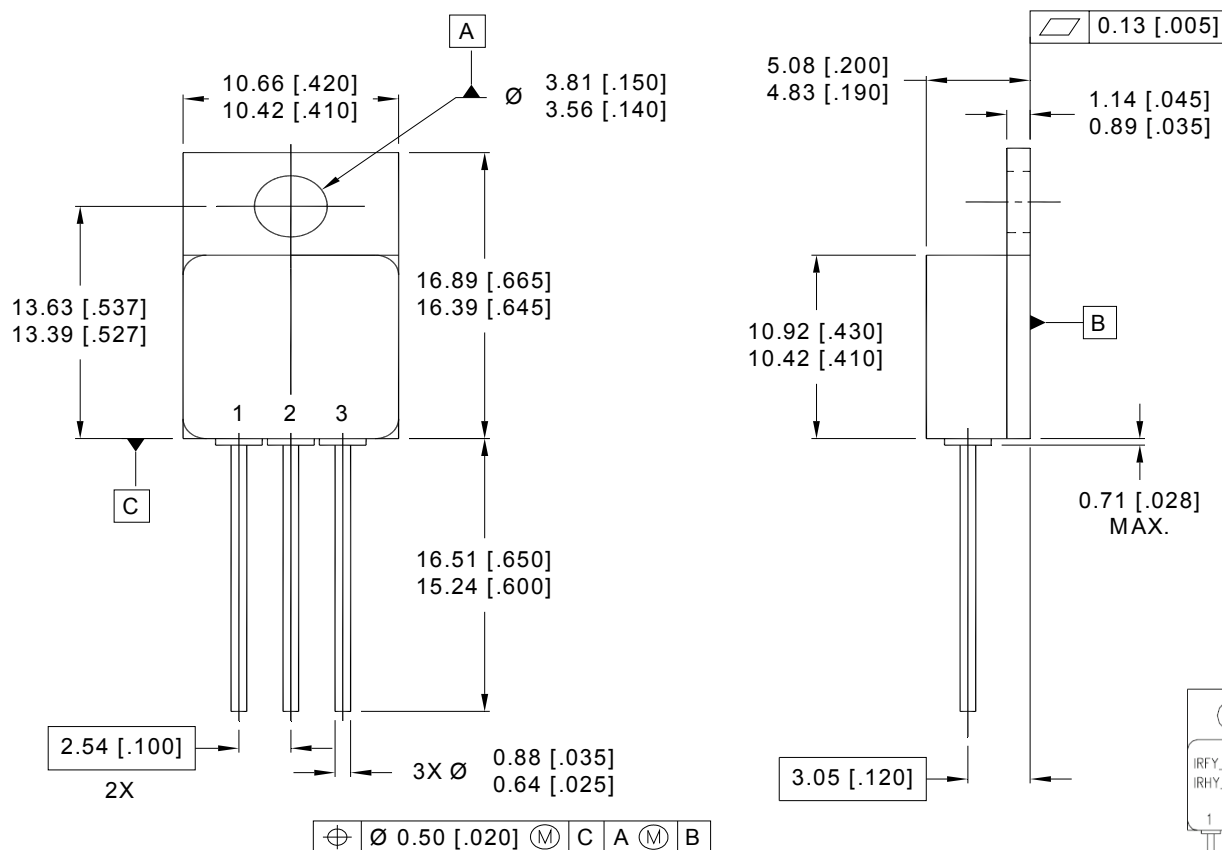


Fig 14b. Switching Time Waveforms

Case Outline and Dimensions - TO257AA



NOTES:

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE TO-257AA.

LEAD ASSIGNMENT

- 1 = DRAIN
- 2 = SOURCE
- 3 = GATE

IMPORTANT NOTICE

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